Institute of Electrical and Electronics Engineers, Inc.

Phoenix Section

Components, Packaging, and Manufacturing Technology Society Chapter
&
Waves and Devices Chapter

PRESENT AN ALL DAY WORKSHOP ON

Devices and Packaging For Wireless Communications

Date:	Friday, December 3rd, 2004	**Time:**	7:00 A.M. - 5:00 P.M.
Location:	Arizona Room, Memorial Union Building, Arizona State University, Tempe, Arizona		

AGENDA

REGISTRATION and CONTINENTAL BREAKFAST: 7:00 A.M. – 8:00 A.M.

WELCOME and INTRODUCTION – Dr. Vasu Atluri, Manager, Intel Corp.: 7:50 A.M. – 8:00 A.M.

MORNING SESSION (Chairs: Dr. Dragan Zupac / Dr. Olin Hartin): 8:00 A.M. – 11:30 A.M.

- **Keynote Talk: Next Generation of Wireless Devices – Challenges and Issues**
  Dr. Sayfe Kiaei – Professor and Director of Connection One, Arizona State University
- **Research Toward More Flexible Radio Systems**
  Dr. Kevin C. Kahn – Senior Fellow, Director, Communications Technology Lab, Intel Corp.
- **Silicon for Millimeter Wave Wireless Applications**
  Dr. Modest M. Oprysko – Department Group Manager, Communication Technologies, IBM Research

BREAK: 9:45 A.M. – 10:00 A.M.

- **Nanoelectronics, Near-Term and Long-Term Opportunities**
  Dr. Stephen M. Goodnick – Chair, Electrical Engineering Department, Arizona State University
- **Modeling and Characterization of Noise and Linearity for RFIC Design**
  Dr. Guofu Niu – Professor, Electrical and Computer Engineering Department, Auburn University
- **Wireless Communication Standards and Regulations**
  Dr. Michael J. Marcus – Associate Chief for Technology (Retired), Office of Eng. and Tech., FCC

BUFFET LUNCH / VENDOR DISPLAYS: 11:30 A.M. – 12:30 P.M.

AFTERNOON SESSION (Chairs: Dr. Rao Bonda / Mr. Sam Karikalan): 12:30 P.M. – 4:00 P.M.

- **Keynote Talk: System-in-Package - Challenges / Directions for Communications and Wireless Products**
  Mr. Ken Brown – Senior Manager, Assembly Technology Development, Intel Corp.
- **Integration of Passives**
  Mr. Dean P. Kossives – Member of Technical Staff, STATS ChipPAC, Inc.
- **High Power RF Packaging for Wireless Infrastructure**
  Dr. Mali Mahalingam – Fellow of Technical Staff and Manager, Freescale Semiconductor, Inc.

BREAK: 2:15 P.M. – 2:30 P.M.

- **Wafer Level Packaging for Wireless Applications**
  Dr. Luu Nguyen, Engineering Manager, National Semiconductor Corp.
- **System Level Packaging for Wireless Applications**
  Dr. Amit Agrawal, Principal Scientist, Signal Integrity and Package Development, Broadcom Corp.
- **Keynote Talk: Enabling Mobility – Future Wireless Technologies**
  Mr. Behrooz Abdi – Vice President and General Manager, Qualcomm Inc.

PANEL DISCUSSION: 4:00 P.M. – 5:00 P.M.

- **Future Market Opportunities in Wireless Communications**
  Moderator: Dr. Chuck Weitzel – Manager, Freescale Semiconductor, Inc.

For General Information
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